

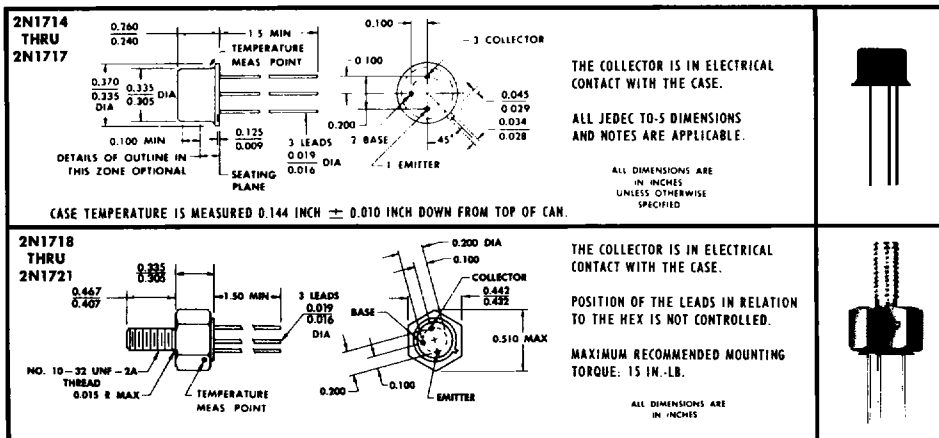
TYPES 2N1714 THRU 2N1721 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPES 2N1714 THRU 2N1721
BULLETIN NO. DL-S-6810483, NOVEMBER 1968

HIGH-FREQUENCY INTERMEDIATE-POWER TRANSISTORS

- 15 Watts at 100°C Case Temperature
- Typ $V_{CE(sat)}$ of 0.2 V at 200 mA
- Typ V_{BE} of 0.8 V at 200 mA
- Typ f_T of 50 MHz at 10 V, 100 mA

***mechanical data**



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absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	2N1714	2N1715	2N1718	2N1719	2N1716	2N1717	2N1720	2N1721
Collector-Base Voltage	90 V*	150 V*	90 V*	150 V*	60 V*	100 V*	60 V*	100 V*
Collector-Emitter Voltage (See Note 1)	60 V*	100 V*	60 V*	100 V*	← 6 V* →			
Emitter-Base Voltage	← 6 V* →							
Continuous Collector Current	← { 1 A† } →							
Peak Collector Current (See Note 2)	← { 0.75 A* } →							
Continuous Emitter Current	← { 1.5 A† } →							
Safe Operating Region at (or below) 100°C Case Temperature	← { 1 A* } →							
Continuous Device Dissipation at (or below) 100°C Case Temperature (See Note 3)	← { 1A† } →							
Continuous Device Dissipation at (or below) 25°C Free-Air Temperature (See Note 4)	← { 0.75 A* } →							
Operating Collector Junction Temperature	← See Figure 10 →							
Storage Temperature Range	← { 15 W† } →							
	← { 10 W* } →							
	← { 1 W† } →							
	← { 0.8 W* } →							
	← { 200°C† } →							
	← { 175°C* } →							
	← -65°C to 200°C* →							

- NOTES: 1. These values apply when the base-emitter diode is open-circuited.
 2. This value applies for $t_p \leq 0.3$ ms, duty cycle $\leq 10\%$.
 3. For operation above 100°C case temperature refer to Dissipation Derating Curve, figure 13.
 4. For operation above 25°C free-air temperature refer to Dissipation Derating Curves, figures 11 and 12.

*Indicates JEDEC registered data
 †Texas Instruments guarantees these values in addition to the JEDEC registered values which are also shown.

TYPES 2N1714 THRU 2N1721

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

*electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	2N1714	2N1715	2N1716	2N1717	UNIT				
		2N1718	2N1719	2N1720	2N1721					
		MIN	MAX	MIN	MAX	MIN	MAX			
$V_{(BR)CEO}$ Collector-Emitter Breakdown Voltage	$I_C = 30 \text{ mA}$, $I_B = 0$, See Note 5	60	100	60	100		V			
I_{CBO} Collector Cutoff Current	$V_{CB} = 3 \text{ V}$, $I_E = 0$	1	1	1	1		μA			
I_{CEO} Collector Cutoff Current	$V_{CE} = 50 \text{ V}$, $I_B = 0$	50		50			μA			
	$V_{CE} = 90 \text{ V}$, $I_B = 0$		50		50		μA			
I_{CES} Collector Cutoff Current	$V_{CE} = 60 \text{ V}$, $V_{BE} = 0$	2	2	2	2		μA			
	$V_{CE} = 90 \text{ V}$, $V_{BE} = 0$	50		50						
	$V_{CE} = 150 \text{ V}$, $V_{BE} = 0$		50		50					
	$V_{CE} = 60 \text{ V}$, $V_{BE} = 0$, $T_C = 170^\circ\text{C}$	500	500	500	500					
I_{EBO} Emitter Cutoff Current	$V_{EB} = 3 \text{ V}$, $I_C = 0$	10	10	10	10		μA			
	$V_{EB} = 6 \text{ V}$, $I_C = 0$	10	10	10	10					
$V_{EB(F)}$ Emitter-Base Floating Potential	$V_{CB} = 60 \text{ V}$, $I_E = 0$	1		1			V			
	$V_{CB} = 100 \text{ V}$, $I_E = 0$		2		2					
h_{FE} Static Forward Current Transfer Ratio	$V_{CE} = 5 \text{ V}$, $I_C = 10 \text{ mA}$, See Note 5	10	10	20	20					
	$V_{CE} = 5 \text{ V}$, $I_C = 200 \text{ mA}$, See Notes 5 and 6	20	60	20	60	40		120	40	120
	$V_{CE} = 5 \text{ V}$, $I_C = 200 \text{ mA}$, See Notes 5 and 6 $T_C = -55^\circ\text{C}$	10	10	20	20					
V_{BE} Base-Emitter Voltage	$I_B = 20 \text{ mA}$, $I_C = 200 \text{ mA}$, See Notes 5 and 6	1.6	1.6	1.6	1.6		V			
$V_{CE(sat)}$ Collector-Emitter Saturation Voltage	$I_B = 20 \text{ mA}$, $I_C = 200 \text{ mA}$, See Notes 5 and 6	2	2	2	2		V			
$ h_{fe} $ Small-Signal Common-Emitter Forward Current Transfer Ratio	$V_{CE} = 10 \text{ V}$, $I_C = 100 \text{ mA}$, $f = 16 \text{ MHz}$	1	1	1	1					
C_{obo} Common-Base Open-Circuit Output Capacitance	$V_{CB} = 10 \text{ V}$, $I_E = 0$, $f = 1 \text{ MHz}$	50	50	50	50		pF			

NOTES: 5. These parameters must be measured using pulse techniques. $I_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

thermal characteristics

PARAMETER	2N1714, 2N1715	2N1718, 2N1719	UNIT
	2N1716, 2N1717	2N1720, 2N1721	
		MAX	MAX
θ_{J-C} Junction-to-Case Thermal Resistance	6.67 [†] 7.5 [*]	6.67 [†] 7.5 [*]	deg/W
θ_{J-A} Junction-to-Free-Air Thermal Resistance	175 [†] 187.5 [*]	75 [*]	

* Indicates JEDEC registered data

† Texas Instruments guarantees these values in addition to the JEDEC registered values which are also shown.

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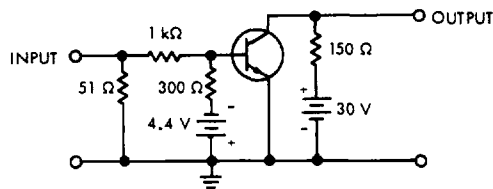
TYPES 2N1714 THRU 2N1721 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

switching characteristics at 25°C case temperature

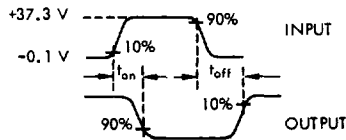
PARAMETER	TEST CONDITIONS†	TYP	UNIT
t_{on} Turn-On Time	$I_C = 200 \text{ mA}$, $I_{B(1)} = 20 \text{ mA}$, $I_{B(2)} = -20 \text{ mA}$,	0.14	μs
t_{off} Turn-Off Time	$V_{BE(off)} = -3.4 \text{ V}$, $R_L = 150 \Omega$, See Figure 1	2.6	

†Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

FIGURE 1

- NOTES:
- The input waveform is supplied by a generator with the following characteristics: $t_r \leq 15 \text{ ns}$, $t_f \leq 15 \text{ ns}$, $Z_{out} = 50 \Omega$, $t_p = 10 \mu\text{s}$, duty cycle $\leq 2\%$.
 - Waveforms are monitored on an oscilloscope with the following characteristics: $t_r \leq 15 \text{ ns}$, $R_{in} \geq 10 \text{ M}\Omega$, $C_{in} \leq 11.5 \text{ pF}$.
 - Resistors must be noninductive types.
 - The d-c power supplies may require additional bypassing in order to minimize ringing.

TYPES 2N1714 THRU 2N1721

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPICAL CHARACTERISTICS

2N1714, 2N1715, 2N1718, 2N1719
 STATIC FORWARD CURRENT TRANSFER RATIO
 vs
 COLLECTOR CURRENT

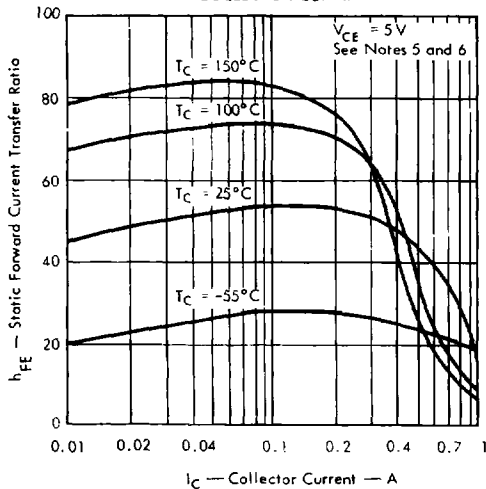


FIGURE 2

2N1716, 2N1717, 2N1720, 2N1721
 STATIC FORWARD CURRENT TRANSFER RATIO
 vs
 COLLECTOR CURRENT

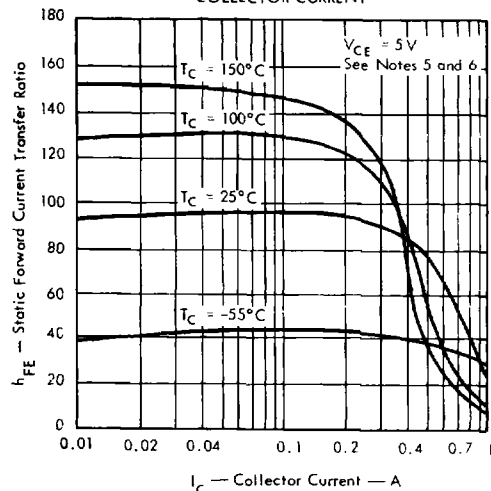


FIGURE 3

BASE-EMITTER VOLTAGE
 vs
 CASE TEMPERATURE

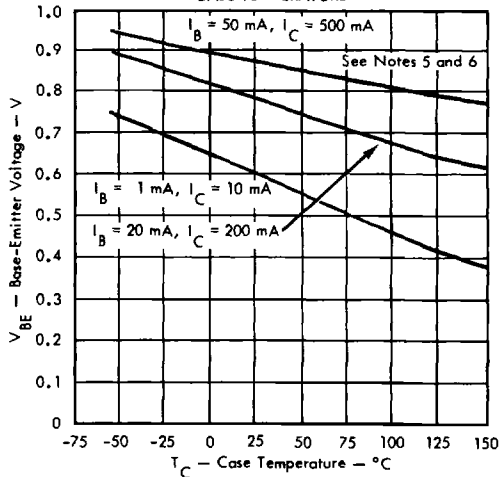


FIGURE 4

COLLECTOR-EMITTER SATURATION VOLTAGE
 vs
 CASE TEMPERATURE

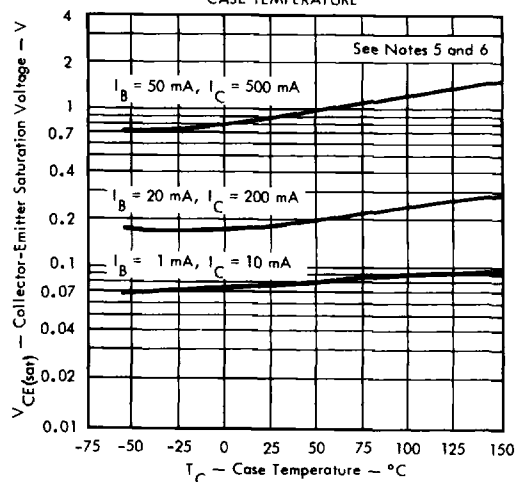


FIGURE 5

NOTES: 5. These parameters must be measured using pulse techniques. $t_p = 300 \mu s$, duty cycle $\leq 2\%$.

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

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TYPES 2N1714 THRU 2N1721

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPICAL CHARACTERISTICS

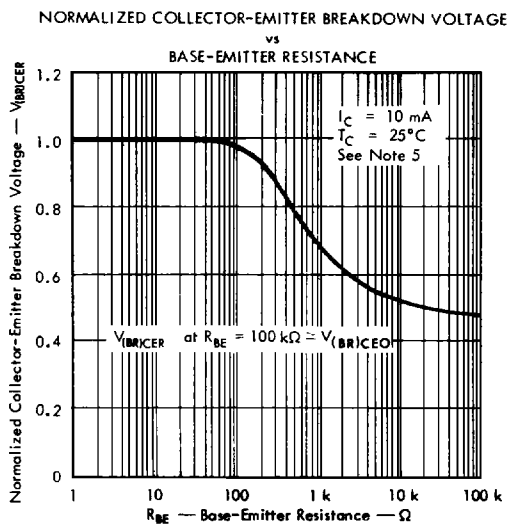


FIGURE 6

2N1714, 2N1715,
2N1718, 2N1719

SMALL-SIGNAL COMMON-EMITTER
FORWARD CURRENT TRANSFER RATIO
vs
FREQUENCY

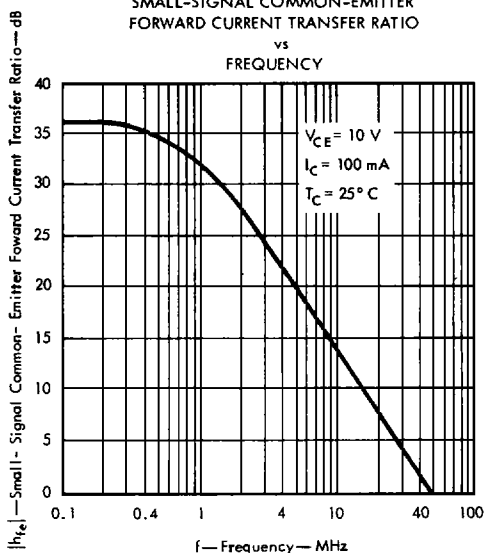


FIGURE 8

NOTE 5: This parameter must be measured using pulse techniques. $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

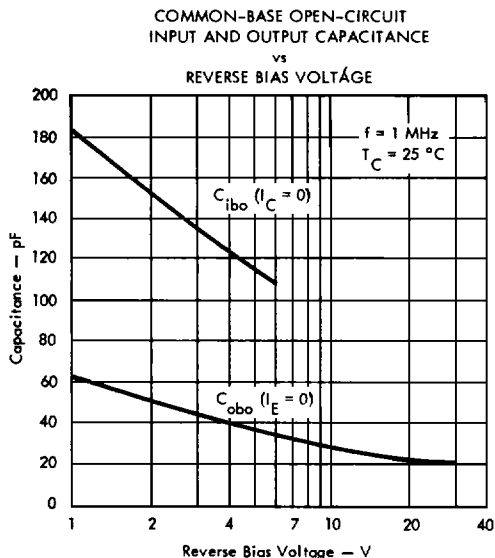


FIGURE 7

2N1716, 2N1717,
2N1720, 2N1721

SMALL-SIGNAL COMMON-EMITTER
FORWARD CURRENT TRANSFER RATIO
vs
FREQUENCY

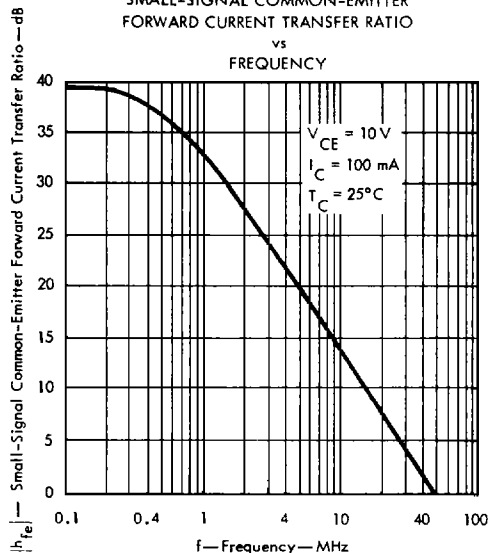


FIGURE 9

TYPES 2N1714 THRU 2N1721

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

MAXIMUM SAFE OPERATING REGION

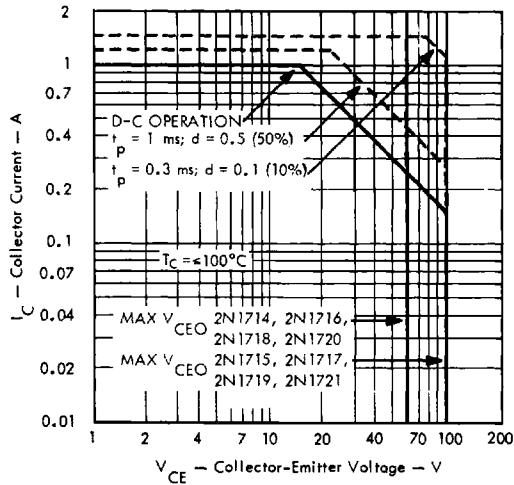


FIGURE 10

THERMAL INFORMATION

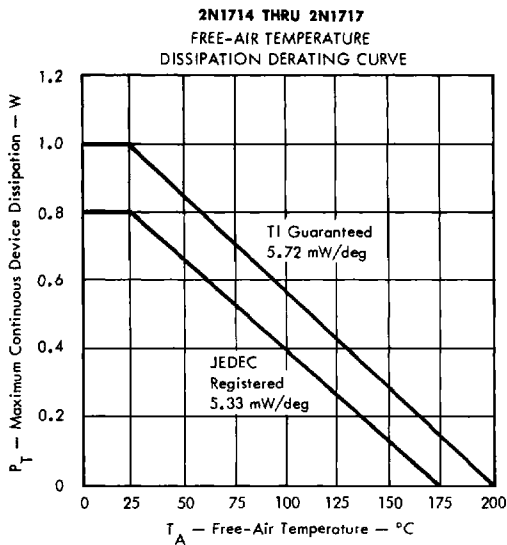


FIGURE 11

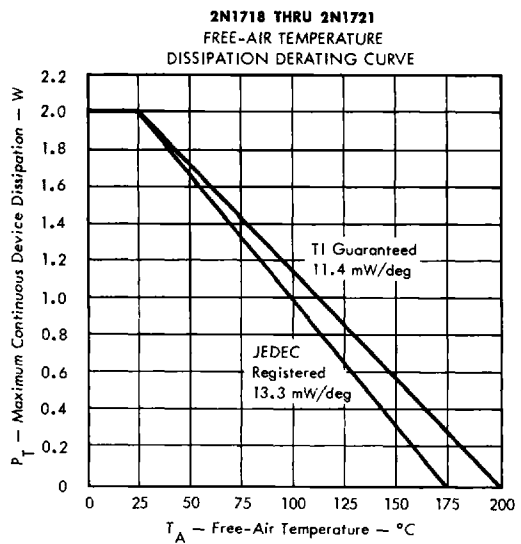


FIGURE 12

TYPES 2N1714 THRU 2N1721 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

THERMAL INFORMATION

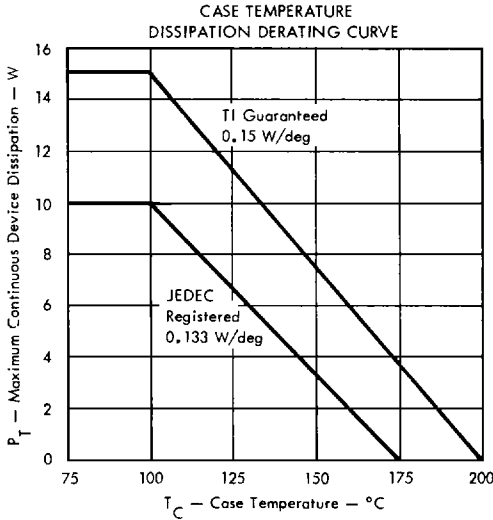


FIGURE 13

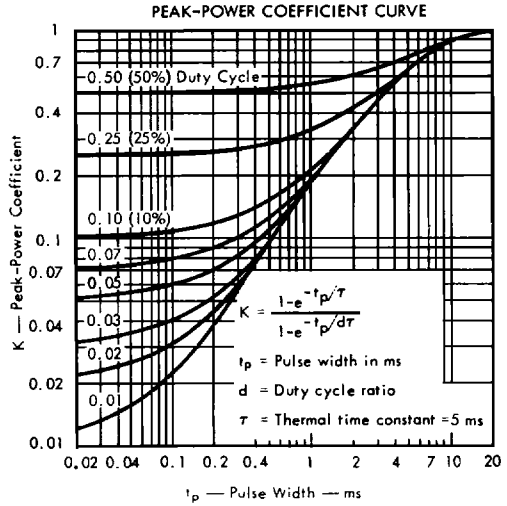


FIGURE 14

SYMBOL DEFINITION

SYMBOL	DEFINITION	VALUE		UNIT
		2N1714 THRU 2N1717	2N1718 THRU 2N1721	
$P_{T(av)}$	Average Power Dissipation			W
$P_{T(max)}$	Peak Power Dissipation			W
θ_{J-A}	Junction-to-Free-Air Thermal Resistance	175	75	deg/W
θ_{J-C}	Junction-to-Case Thermal Resistance	6.67	6.67	deg/W
θ_{C-A}	Case-to-Free-Air Thermal Resistance	168	68	deg/W
θ_{C-HS}	Case-to-Heat-Sink Thermal Resistance			deg/W
θ_{HS-A}	Heat-Sink-to-Free-Air Thermal Resistance			deg/W
T_A	Free-Air Temperature			°C
T_C	Case Temperature			°C
$T_{J(av)}$	Average Junction Temperature	≤ 200		°C
$T_{J(max)}$	Peak Junction Temperature	≤ 200		°C
K	Peak-Power Coefficient	See Figure 14		
t_p	Pulse Width			ms
t_r	Pulse Period			ms
d	Duty-Cycle Ratio (t_p/t_r)			

Example — Find $P_{T(max)}$ (design limit)

OPERATING CONDITIONS:

$$\theta_{C-HS} + \theta_{HS-A} = 7 \text{ deg/W (from information supplied with heat sink.)}$$

$$T_{J(av)} \text{ (design limit)} = 200^\circ\text{C}$$

$$T_A = 50^\circ\text{C}$$

$$d = 10\% (0.1)$$

$$t_p = 0.1 \text{ ms}$$

Equation No. 1 — Application: d-c power dissipation, heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-C} + \theta_{C-HS} + \theta_{HS-A}} \text{ for } 100^\circ\text{C} \leq T_C \leq 200^\circ\text{C} \text{ as in Figure 13}$$

Equation No. 2 — Application: d-c power dissipation, no heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-A}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Equation No. 3 — Application: Peak power dissipation, heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K \theta_{J-C}} \text{ for } 100^\circ\text{C} \leq T_C \leq 200^\circ\text{C}$$

Equation No. 4 — Application: Peak power dissipation, no heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d \theta_{C-A} + K \theta_{J-C}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Solution:

From Figure 14, Peak-Power Coefficient

$$K = 0.11 \text{ and by use of equation No. 3}$$

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K \theta_{J-C}}$$

$$P_{T(max)} = \frac{200 - 50}{0.1(7) + 0.11(6.67)} = 105 \text{ W}$$